

01-24-2003

Attorney Docket No.: AB-748 US

FORM PTO-1595
(REV. 03/01)

RE

EET

U.S. DEPARTMENT OF COMMERCE

U.S. Patent and Trademark Office



102346118

To the Honorable Commissioner of Patent and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

(a) Anam Semiconductor, Inc.

1-21-03

2. Name and address of receiving party(ies):

Name: Amkor Technology Korea, Inc.

Internal Address:

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of Conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Other

Execution Date:

Street Address: 280-8, 2-ga, Sungsu-dong

Sungdong-gu,
City: Seoul

Country: Korea

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s): 09/240,423, Patent No. 6,214,645

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s) -

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Skjerven Morrill LLP

Internal Address:

Street Address: 25 Metro Drive, Suite 700

City: San Jose

State: CA

Zip: 95110

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

☒ Enclosed

☒ Authorized to be charged to Deposit Account

8. Deposit account Number: 19-2386

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

James E. Parsons, Reg. No. 34,691

Name of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments, and documents: 1

Mail document to be recorded with required cover sheet information to:

01/24/2003 ECOOPER 00000010 192386

09240423

01 FC:0021

40.00 CH

Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

908408

PATENT
REEL: 013678 FRAME: 0203

INTELLECTUAL PROPERTY TRANSFER AGREEMENT

THIS INTELLECTUAL PROPERTY TRANSFER AGREEMENT (the "Agreement") is entered into effective as of May 2, 2000 (the "Effective Date"), by and between Amkor Technology Korea, Inc. ("AT Korea"), a corporation organized under the laws of the Republic of Korea, and Anam Semiconductor, Inc. ("Anam"), a corporation organized under the laws of the Republic of Korea and having offices in Seoul, Korea (each of AT Korea and Anam, a "Party"; together, the "Parties").

WITNESSETH:

WHEREAS, the Parties have entered into that certain "Asset Purchase Agreement" dated as of January 14, 2000, as amended from time to time, ("APA") pursuant to which AT Korea shall acquire from Anam certain assets related to the facilities for semiconductor packaging and test operations generally known as K-1, K-2 and K-3 ("Facilities");

WHEREAS, in connection with such acquisition, AT Korea will acquire the "Intellectual Property" (as such term is defined in the APA) from Anam;

NOW, THEREFORE, in consideration of the mutual covenants and promises contained herein, the Parties hereby agree as follows:

Article 1. Transfer of Intellectual Property

Anam hereby irrevocably transfers, conveys and assigns to AT Korea in perpetuity all worldwide right, title and interest in and to the Intellectual Property, including the Assigned Intellectual Property as set forth in Schedule 2.16 of the APA, and the "Confidential Information" (as such term is defined in 1.13 (g) of the APA).

Article 2. Warranties and Indemnities

- 2.1. Anam hereby represents and warrants to AT Korea that, to the best of Anam's knowledge: (i) the Intellectual Property and AT Korea's use thereof will not infringe any intellectual property rights of any third party; (ii) the Intellectual Property is not subject to any third-party lien or encumbrance; (iii) no third party is infringing or misappropriating or has infringed or misappropriated the

Intellectual Property; and (iii) all the Intellectual Property transferred to AT Korea hereunder is valid and subsisting, and no grounds exist to invalidate or render unenforceable any such Intellectual Property.

- 2.2 Anam shall indemnify and hold AT Korea, its affiliates and customers harmless from and against all loss, cost, liability, damage and expense suffered or incurred by any of them in connection with any breach by Anam of any warranty set forth herein.

Article 3. Registration of Transfer of Intellectual Property

- 3.1 AT Korea shall file an assignment registration of the Intellectual Property with the Korean Industrial Property Office ("KIPO") in the name of AT Korea after it receives the necessary documents for assignment recordation of the Intellectual Property from Anam.
- 3.2 Anam shall fully cooperate with AT Korea for the title transfer of the Intellectual Property to AT Korea including any and all documentary requirements and procedures.
- 3.3 Anam shall provide to AT Korea the necessary documents for assignment recordation of the Intellectual Property at the KIPO within fourteen (14) days from the execution date of this Agreement.

Article 4. Effectiveness of Agreement

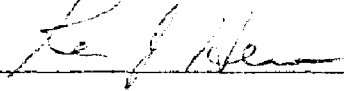
This Agreement shall be effective upon execution hereof, and continue in full force and effect until the Parties agree to mutually terminate this Agreement.

Article 5. Governing Law and Jurisdiction

This Agreement shall be governed and interpreted by the laws of the Republic of Korea and any dispute between the parties shall be subject to the jurisdiction of the Seoul District Court.

IN WITNESS WHEREOF, the Parties have caused this Agreement to be executed by duly authorized officers or representatives to be effective as of the date first above written.

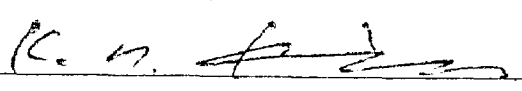
Amkor Technology Korea, Inc.

By: 

Name: _____

Title: _____

Anam Semiconductor, Inc.

By: 

Name: _____

Title: _____

USA Patent List

#	ATK Ref.	Attorney Docket	Appl No	Title	Inventor(s)	File Date	Korean Priority Apps.	Priority Date	Patent No	Issue Date	Assignee	Remark
1	US-018		08/214339	Mold runner removal from a substrate-based packaged electronic device	Young Wook Heo / Il Kwon Shim / Bruce J. Freyman / John Briar	94-3-16	93-15985	93-08-18	5,635,671	97-6-3	Anam & Ankor	
2	US-018-1		08/756777	Mold runner removal from a substrate-based packaged electronic device	Young Wook Heo / Il Kwon Shim / Bruce J. Freyman / John Briar	96-11-26	93-15985	93-08-18			Anam & Ankor	Rejection
3	US-026		08/729540	Method for molding of integrated circuit package	Goo Lee	96-10-11	93-25829 / 94-22439 / 94-22439 / 94-22439	93-11-30 / 94-09-07 / 94-09-07	5,637,273	97-6-10	Anam & Ankor	
4	US-026-1		08/349237	Method and device for molding of integrated circuit package(Device)	Goo Lee	94-10-5	93-25829 / 94-22439 / 94-22439	93-11-30 / 94-09-07 / 94-09-07			Anam & Ankor	Rejection
5	US-043		08/275177	Method of reducing delamination between a lead frame and molding compound	Jae Dong Kim / Richard Cooley	94-7-14	94-5635 / 94-15873	94-03-21 / 94-07-02			Anam & Ankor	Rejection
6	US-069		08/485936	adhesive composition for semiconductor	Choul Woll Kwak	95-6-7	94-13647	94-06-16	5,582,772	96-12-10	Anam & Ankor	
7	US-071	M-3384 US	08/479885	Heat spreader suitable for use in semiconductor packages having different	Myung Jun Lee	95-5-7	94-14028	94-06-21	5,641,987	97-6-24	Anam & Ankor	
8	US-090		08/520429	Semiconductor leadframe having connection bar and guide rings	Won Sun Shin	95-8-29	94-21619 / 94-26326 / 94-26326	94-08-30 / 94-10-10 / 94-10-10	5,723,899	98-3-3	Anam & Ankor	
9	US-105	AB-427 US	08/530558	Method for checking a wire bond of a semiconductor package	Young Wook Heo / Dong Sin Youm / Young Chul Yoo / Hee	95-9-19	94-24280	94-08-27	5,712,570	98-1-27	Anam & Ankor	
10	US-141	AB-444 US	08/571316	Chip mounting plate construction of lead frame for semiconductor package	Yeoul Yoo / Jeong Lee / Doo Hyun Park / In Gyu	95-12-12	94-33994 / 94-37168	94-12-14 / 94-12-27	5,661,338	97-8-26	Anam & Ankor	
11	US-148	AB-445 US	08/570794	Semiconductor package with integral heat dissipator	Won Sun Shin / Byung Tae Do	95-12-12	94-34663	94-12-16	5,629,561	97-5-13	Anam & Ankor	
12	US-208		08/641023	Method for leveling solder ball array in BGA semiconductor package	Young Wook Heo	96-4-29	95-10418	95-04-29			Anam & Ankor	Rejection
13	US-227	AB-452 US	08/588482	Method and circuit board structure for leveling solder balls in BGA semiconductor	Il Kwon Shim / Young Wook Heo	96-1-18	95-19581	95-07-05	5,641,946	97-6-24	Anam & Ankor	
14	US-228		08/588172	Ball grid array semiconductor packages with improved heat dissipation and dehumidification effect	Il Kwon Shim / Young Wook Heo	96-1-18	95-19582	95-07-05	5,729,432	98-3-17	Anam & Ankor	
15	US-245		08/707381	Method for fabricating a heat sink-interated semi-conductor package	Won Sun Shin	96-9-4	95-28771	95-09-04	5,807,768	#####	Anam & Ankor	
16	US-246		08/570849	Bonding method for semiconductor chips	Seong Min Seo / Sunk Ju Jang	95-12-12	95-28772	95-09-04	5,740,956	98-4-21	Anam & Ankor	
17	US-266		08/736107	Printed circuit board having epoxy barrier around a through slot and ball grid array semiconductor package	Sun Ho Ha / Young Wook Heo	96-10-24	95-37513	95-10-27	5,767,446	98-6-16	Anam & Ankor	
18	US-271	AB-467 US	08/748937	Ball grid array semiconductor package with ring-type heat sink	Il Kwon Shim / Young Wook Heo	96-11-13	95-41438	95-11-15	5,708,567	98-1-13	Anam & Ankor	
19	US-280		08/749450	Semiconductor package including heat sink with layered conductive plate and non-conductive tape bonding to leads	Won Sun Shin / Won Kym Lee	96-11-14	95-41844 / 95-44554	95-11-17 / 95-11-29	5,854,511	#####	Anam & Ankor	
20	US-282		08/651200	Unit printed circuit board carrier frame for ball grid array semiconductor package and method for fabricating ball grid array	Il Kwon Shim / Young Wook Heo	96-5-17	95-41846	95-11-17	5,854,741	#####	Anam & Ankor	
21	US-286		08/749578	Process for bonding semiconductor chip	Seong Min Seo / Jae Hwan Song	96-11-14	95-42561	95-11-21	5,858,149	#####	Anam & Ankor	

#	ATK Ref.	Attorney Docket	Appl No	Title	Inventor(s)	File Date	Korean Priority Apps.	Priority Date	Patent No	Issue Date	Assignee	Remark
22	US-295		08/777927	Semiconductor chip scale package and method of producing such	Young Wook Heo	96-12-23	95-54765	95-12-12	5,915,169	#####	Anam & Amkor	
23	US-301		08/777926	Semiconductor package lead frame with stress absorbing means on fused leads	Kil Bum Kim / Young Seok Chung	96-12-23	95-58806	95-12-27			Anam & Amkor	Rejection
24	US-389		08/704477	Wafer map conversion method	Chee Jung Song	96-8-28	96-05343	96-12-29	5,838,951	98-11-17	Anam & Amkor	
25	US-391		08/775212	Ball grid array semiconductor package using a metal carrier ring as a heat spreader	Il Kwon Shim / Young Wook Heo	96-12-31	96-05345	96-02-29	5,905,633	#####	Anam & Amkor	
26	US-393		08/813725	Method of forming chip bumps of bump chip scale semiconductor package	Young Wook Heo	97-3-7	96-06302 / 96-06303	96-03-11	5,908,317	#####	Anam & Amkor	
27	US-399		08/825945	Solder Ball land metal structure of ball grid array semiconductor package	Moo Eun Lee Woon Sun Shim / Byung Joon Han / Ju Hoon Yoon / Sung Bum Kwak / In Gyu	97-4-1	96-09778	96-04-01	5,872,399	99-2-16	Anam & Amkor	
28	US-418	AB-510 US	08/775839	Leads and grid array semiconductor package	Byung Joon Han / Young Wook Heo	96-12-11	96-22901	96-06-21	5,858,815	#####	Anam & Amkor	
29	US-422		08/763605	Semiconductor package and method for fabricating the same	Byung Joon Han / Young Wook Heo	98-1-16	96-22901	96-06-21	5,977,624	#####	Anam & Amkor	
30	US-422-1		09/008552	Semiconductor package and assembly for fabricating the same	Young Yeob Moon	97-9-19	96-41469 / 70 / 71 / 72 / 96-58810 / 11 / 15 / 16	96-09-21 / 96-11-28	5,971,734	#####	Anam & Amkor	
31	US-455		08/934315	Mold for ball grid array semiconductor package	Seon Goo Lee	97-10-2	96-43843 / 96-46656	96-10-04 / 96-10-18	5,986,334	#####	Anam & Amkor	
32	US-461		08/942784	Semiconductor package having light, thin simple and compact structure Method for reproducing printed circuit boards for semiconductor packages	Young Wook Heo / Il Kwon Shim	97-6-25	96-62305	96-12-06	6,021,563	#####	Anam & Amkor	
33	US-494		08/951062	including poor quality printed circuit board units and method for fabricating semiconductor packages using the	Sun Ho Ha / Young Wook Heo / Byung Joon Han	97-10-15	96-46948	96-10-19	5,897,334	#####	Anam & Amkor	
34	US-544		08/882687	Marking bad printed circuit boards for semiconductor packages	Young Wook Heo / Il Kwon Shim	97-6-25	96-62305	96-12-06	6,021,563	#####	Anam & Amkor	
35	US-573		08/882248	Printed circuit board for ball grid array semiconductor package	Young Wook Heo	97-6-25	96-74120	96-12-27	5,981,873	#####	Anam & Amkor	
36	US-575		08/951890	Method for manufacturing an alumina-silicon carbide nanocomposite	Seok Ho Na	97-10-16	96-77897	96-12-30	5,894,008	#####	Anam & Amkor	
37	US-576	AB-564 US	08/915077	Ball grid array semiconductor package with solder balls fused on printed circuit board and method for fabricating the same	Il Kwon Shim / Young Wook Heo / Robert Francis Darveaux	97-8-20	96-77898 / 96-77899 / 97-04430	96-12-30 / 97-02-14	5,953,589	#####	Anam & Amkor	
38	US-578		08/883541	Flexible circuit for ball grid array semiconductor package	Il Kwon Shim / Young Wook Heo / Robert Francis Darveaux	97-6-25	96-77900 / 96-77901 / 96-77902	96-12-30	5,864,470	#####	Anam & Amkor	
39	US-591	AB-602 US	08/998591	Circuit board with eye-shaped internal circuit tip alignment structure for mounting electronic components	Joong Ho Cho / Young Seok Chung / Kyung Sook Choi	97-12-29	96-77919	12/30/1996			Anam & Amkor	Rejection
40	US-611	AB-606 US	09/013330	Method of manufacturing ball grid array semiconductor package	Il Kwon Shim / Sun Ho Ha / Robert Francis Darveaux	98-1-26	97-02504	01/28/1997	6,020,218	00-2-1	Anam & Amkor	
41	US-627		09/024925	Circuit board	Sang Suk Cha	98-2-17	97-04656	02/17/1997			Anam & Amkor	Rejection
42	US-632	AB-609 US	09/024940	Method of fabricating semiconductor package	Young Wook Heo	98-2-17	97-06063	02/26/1997	Notice of allowance		Anam & Amkor	
43	US-860		09/063380	Semiconductor device and manufacturing method of the same	Hee Yeoul Yoo / Kanako Sawada / Atsushi Kurosu / Kenji Takahashi	98-4-21	平9-105024 (Japan)	04/22/1997	5,937,279	#####	ATK / Toshiba	Assignment is done

#	ATK Ref.	Attorney Docket	Appl No	Title	Inventor(s)	File Date	Korean Priority Apps. (Only US)	Priority Date	Patent No	Issue Date	Assignee	Remark
44	US-5897	M-5897 US	09/176614	Plastic Integrated Circuit Package And Micro-Leadframe And Method For Making	Jae Hak Yee/Thomas P. Glenn/ Scott Jewler,	98-10-21	None(Only US)	None	6,81,568	#####	Anam & Ankor	
45	US-873	AB-748 US	09/240423	The PCB for BGA Semiconductor PKG	Kim Sung Jin	99-1-29	98-19304,36897,36898	98-05-27,98-09-08	6,246,015	#####	Anam & Ankor	
46	US-872	AB-747 US	09/240422	Method of molding BGA Semiconductor PKG	Kim Sung Jin	99-1-29	98-19303,19304,36897,36898	98-05-27,98-09-08	6,212,645	#####	Anam & Ankor	
47	US-418-1	AB-510-1D US	09/203,720	Grid array type lead frame and lead end grid array semiconductor package employing the same	Won-Sun Shim / Byung Joon Han / Ju Hoon Yoon / Sung Bum Kwak / In Gyu	98-12-1	96-22897 / 96-22898 / 96-22899	06/21/1996	6,150,709	#####	Anam & Ankor	
48	US-877	AB-726 US	09/238,468	Semiconductor Package With Multilevel Lead Frame	Sun Jin Son	99-1-28	98-21720	06/11/1998			Anam & Ankor	Rejection
49	US-393-1	AB-513-1D US	09/222,226	Bump Chip Scale Semiconductor Package	Young Wook Heo	98-12-29	96-06302 / 96-06303	96-03-11	6,091,141	#####	Anam & Ankor	
50	US-782	AB-812 US	09/305,170	PCB With Oval Solder Ball Lands For BGA Semi. PKG	Kim Sung Jin	99-5-4	None	None	6,268,568	#####	Anam & Ankor	
51	US-861	AB-811 US	09/287,711	Thin, Stackable Semiconductor Packages	Lee Seon Goo	99-4-7	98-12364	04/08/1998	6,303,997	#####	Anam & Ankor	
52	US-576-1	AB-564-1D US	09/309,448	Ball Grid Array semiconductor package with solder balls on printed circuit board and	Il Kwon Shim / Young Wook Heo / Robert Francis	99-5-11	96-77898 / 96-77899 / 97-	96-12-30 / 97-02-14			Anam & Ankor	Pending
53	US-860-1		09/336,697	Semiconductor device and manufacturing method of the same	Hee Yeoul Yoo / Kanako Sawada / Atsushi Kurosu / Kenji Takahashi	99-6-21	98-105024 (Japan)	04/22/1997	6,087,715	#####	ATK / Toshiba	Assignment is done
54	US-884		09/347,794	Adhesive Composition For Bonding Semiconductor Chips	JSKwak/BHMoon	99-7-6	98-27292	07/07/1998	6,225,378	#####	ATK / ATL / NSC	Assignment is processing
55	US-938	AB-886 US	09/422,115	Semiconductor Device and method of manufacturing such device	Park/B/Han/D/Caprio/Hoff	10/20/1999	98-46566,46572	10/31/1998			Anam & Ankor	Pending
56	US-945	AB-885 US	09/421,918	Semiconductor Device and method of manufacturing such device	IK Shim / CK	10/20/1999	98-46573	10/31/1998			Anam & Ankor	Pending
57	US-936	AB-884 US	09/422,027	CSP Semiconductor Package of the Fan-out type and method of manufacturing such	IK Shim / BJ Han / CK Park	10/20/1999	98-46564,46567/4	10/31/1998			Anam & Ankor	Pending
58	US-906	AB-858 US	09/385,694	Wafer-scale production of CSP sing wafer mapping techniques	JHYoon/DBKang/IBPark/Vincent Dicaprio/Markus		98-35620,35622/3	08/31/1998			Anam & Ankor	Pending
59	US-891		09/387,377	Circuit pattern tape for wafer-scale production of CSP	JHYoon/DBKang	08/30/1999	98-35605,35606/3	08/31/1998			Anam & Ankor	Pending
60	US-894	AB-860 US	09/385,695	Method for laminating circuit pattern tape on semiconductor wafer	JHYoon/WHKong/CBLee/SY Yang	08/30/1999	98-35608,35617/3	08/31/1998	Notice of allowance		Anam & Ankor	Pending
61	US-922	AB-866 US	09/391,792	Lead Frame for fabrication of semiconductor packages and semiconductor package	YH Choi	09/08/1999	98-37969	09/15/1998			Anam & Ankor	Pending
62	M-5897-1D	M-5897-1D US	09/395,875	Plastic Integrated Circuit Package And Micro-Leadframe And Method For Making	Jae Hak Yee/Thomas P. Glenn/ Scott Jewler,	99-9-14	09-176,614	10/21/1998			Anam & Ankor	Pending
63	US-1028	AB-928 US	09/513,067	Non-Exposed Heat Sink for semiconductor package	Christopher/Lucian/GJ Kim /SMK in/JALee	00-2-24	99-13130	04/14/1999			Anam & Ankor	Pending
64	US-970	AB-908 US	09/444,035	LFF with lead separator preventing means, semiconductor package using the lead frame and method for fabricating the	JHYee/YSC Chung/JJ Lee	99-11-19	98-49887,52924/63126	98-11-20,98-12-03,98-12-31			Anam & Ankor	Pending
65	US-1029	M-7664 US	09/370,600	Electronic device and L/F and method for making the same	Eulogia/NTKhan/Ludovic o/YH Choi	08/09/1999	98-37969	09/15/1998	6,258,629	01-7-10	Anam & Ankor	

#	ATK Ref.	Attorney Docket	Appl No	Title	Inventor(s)	File Date	Korean Priority Apps.	Priority Date	Patent No	Issue Date	Assignee	Remark
66	US-1000	AB-909 US	09/461,523	Semiconductor package and method for fabricating the same	JiYoung Chung	12/14/1999	98-63822	12/31/1998	Notice of allowance		Anam & Amkor	Pending
67	US-1003	AB-910 US	09/461,629	A Wire For a Semiconductor Package	JSKwak/CHWoo	12/14/1999	98-60456	12/29/1998			Anam & Amkor	Pending
68	M-7989	M-7898 US	09/490,317	Package for stacked integrated circuits and method of making	IKShin/Vincent DiCaprio/Paul Hoffman/BJHan	01/24/2000	N/A	N/A	Notice of allowance		Anam & Amkor	Pending
69	US-1028-D	AB-816 US	09/513,232	Non-Exposed HS MQFP PQ5	GJKim/SMKim/JALee	00-2-24	99-13130	04/14/1999			Anam & Amkor	Pending